

Amendments to the Claims:

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Please amend the claims as follows:

Claim 1 (Currently Amended): A transparent conductive multi-layer structure, comprising:

a substrate overlaid with a support which in turn is overlaid with a conductive layer containing fine conductive particles, said multi-layer structure having a surface resistivity of $10 - 10^3 \Omega/\square$ and a visible light transmittance of at least 70%,

wherein the conductive layer is overlaid with a hard coating layer selected from among a silicone-based hard coating layer and a UV curable hard coating layer.

Claim 2 (Currently Amended): The transparent conductive multi-layer structure according to claim 1, wherein the fine conductive particles are ~~the~~ fine particles of indium-tin oxide.

Claim 3 (Original): The transparent conductive multi-layer structure according to claim 1, wherein the substrate is a glass panel or a resin panel.

Claim 4 (Canceled).

Claim 5 (Original): The transparent conductive multi-layer structure according to claim 1, which has a haze value of 1 - 10%.

Claim 6 (Withdrawn): A process for producing the transparent conductive multi-layer structure of claim 1 which comprises producing a transparent conductive film by applying a dispersion of fine conductive particles onto a support, drying the applied coating to form a

layer containing the fine conductive particles, compressing the layer to form a compressed layer of the fine conductive particles, and thereafter applying thusly produced transparent conductive film on a substrate.

Claim 7 (Withdrawn): The process according to claim 6, wherein the dispersion of the fine conductive particles is substantially free of a binder resin.

Claim 8 (Currently Amended): A transparent conductive multi-layer structure, comprising:

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a substrate overlaid with a conductive layer containing fine conductive particles, said multi-layer structure having a surface resistivity of $10 - 10^3 \Omega/\square$ and a visible light transmittance of at least 70%,

wherein the conductive layer is overlaid with an anchor coating layer and a hard coating layer in that order, and

wherein the hard coating layer is selected from among a silicone-based hard coating layer and a UV curable hard coating layer.

Claim 9 (Currently Amended): The transparent conductive multi-layer structure according to claim 8, wherein the fine conductive particles are ~~the~~ fine particles of indium-tin oxide.

Claim 10 (Original): The transparent conductive multi-layer structure according to claim 8, wherein the substrate is a glass panel or a resin panel.

Claim 11 (Canceled).

Claim 12 (Original): The transparent conductive multi-layer structure according to claim 8, which has a haze value of 1% to less than 10%.

Claim 13 (Original): The transparent conductive multi-layer structure according to claim 8, which has a haze value of 10 - 50%.

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Claim 14 (Withdrawn): A process for producing the transparent conductive multi-layer structure of claim 8 which comprises producing a transparent conductive film by applying a dispersion of fine conductive particles onto a support, drying the applied coating to form a layer containing the fine conductive particles, then compressing said layer to form a compressed fine conductive particles layer, and subsequently adhering to a substrate said compressed fine conductive particle layer of the transparent film, and thereafter stripping away the support from the compressed conductive layer.

Claim 15 (Withdrawn): A process for producing the transparent conductive multi-layer structure of claim 8 which comprises preparing a support overlaid with a hard coating layer and an anchor coating layer in the order, producing a transparent conductive film by applying a dispersion of fine conductive particles onto the anchor coating layer, drying the applied coating to form a layer containing the fine conductive particles, then compressing said layer to form a compressed fine conductive particles layer, and subsequently adhering to a substrate said compressed fine conductive particles layer, and thereafter stripping away the support from the hard coating layer.

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Claim 16 (Withdrawn): The process according to claim 14 or 15, wherein the dispersion of the fine conductive particles is substantially free of a binder resin.
